ASSOCIATION CON ELECTRONICS INC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.			under both	This docume level parts, th	ent is a declar he declaratio	ration of the second se	of the substances mpasses all lowe	within th er level m	e manufactur aterials for w	rer listed ite hich the m	em. Note: anufactur	: if the item is an as er has engineering	sembly with low responsibility.	
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier In	oformation														
Company name* Company unique ID					Unique ID Authority						Response Date*				
nsemi											2025-05-	2025-05-13			
Contact Name	e		Title - Contact]	Phone - Contact*				Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative]	Phone - Representative*				Email - Representative*				
Product-Env-	-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Re	Requester Item Number Mfr Item NOIX4SI NOIX4SI		Number Mfr Item Name			Effective Da	ate V	Version Manufacturing Site		v	/eight*	UOM	Unit Type		
			F3000B-LTI XGS3MP, 4.7CRA, 16port, Color			or	2025-05-13 TA1			1	189.09	mg	Each		
Ianufactu	ring Proccess Information	l		1			1							I	1
Ter	Terminal Plating / Grid Array Material Term		erminal Base A	loy J-STD-020 MSI		L Rating	Peak Proces		ss Body Temperature Max Time at I		Time at Peak	k Temperature Number		mber of Reflow Cycles	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy	y 4			245		С	30		second	s 3			
Comments															
or more info	rmation regarding material com	position	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
irective 2015/863/EU amending RoHS irective 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).												
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	220.55	mg		Misc.	proprietary data		0.8381	mg
			Supplier	Silicon (Si)	7440-21-3		217.5285	mg
			Supplier	Aluminum (Al)	7429-90-5		2.1834	mg
Die Attach Epoxy	45.39	mg	Supplier	2,2-bis(acryloyloxymethyl)butyl acrylate	15625-89-5		34.0425	mg
			Supplier	Imidazole Addition	68490-66-4		1.3617	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		6.8085	mg
			Supplier	Silica (SiO2)	14464-46-1		3.1773	mg
Imaging Lens	456.52	mg	Supplier	Sulfur (S)	7704-34-9		2.2826	mg
			Supplier	Titanium Dioxide (TiO2)	13463-67-7		22.826	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		22.826	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		22.826	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		22.826	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		22.826	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		22.826	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		317.2814	mg
Lid Attach	5.77	mg		Epoxy resin	proprietary data		4.6679	mg
			Supplier	Adeka Optomer SP 150	125054-47-9		0.1385	mg
			Supplier	Photoinitiator	Proprietary Data		0.427	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.5366	mg
Mold Compound-Black	256.37	mg		Phenolic Resin	proprietary data		38.4555	mg
			Supplier	Oxirane	39817-09-9		38.4555	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		7.6911	mg
			Supplier	Carbon Black (C)	1333-86-4		2.5637	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		164.0768	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		5.1274	mg
ubstrate	202.55	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		42.9406	mg
			Supplier	Inorganic filler	Proprietary Data		26.4935	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		2.6534	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.6482	mg
			Supplier	Acetophenone Derivative	Proprietary Data		3.97	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6684	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.6684	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	7.94	mg
			Supplier	Copper (Cu)	7440-50-8	96.0492	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	20.5183	mg
Wire Bond - Au	1.94	mg	Supplier	Gold (Au)	7440-57-5	1.94	mg